LOW SKEW, 1-TO-5, DIFFERENTIAL-TO-HSTL FANOUT BUFFER

ICS85214

PRODUCT DISCONTINUATION NOTICE - LAST TIME BUY EXPIRES MAY 6, 2017

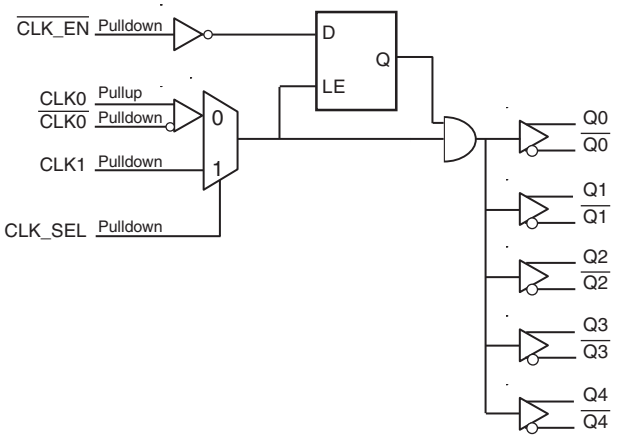
General Description

The ICS85214 is a low skew, high performance 1-to-5 Differential-to-HSTL Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from IDT. The CLK0, $\overline{CLK0}$ pair can accept most standard differential input levels. The single ended CLK1 input accepts LVCMOS or LVTTL input levels. Guaranteed output and part-to-part skew characteristics make the ICS85214 ideal for those clock distribution applications demanding well defined performance and repeatability.

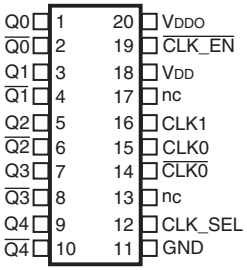
Features

- Five differential HSTL compatible outputs
- Selectable differential CLK0, $\overline{CLK0}$ or LVCMOS/LVTTL clock inputs
- CLK0, $\overline{CLK0}$ pair can accept the following differential input levels: LVPECL, LVDS, HSTL, HCSL, SSTL
- CLK1 can accept the following input levels: LVCMOS or LVTTL
- Output frequency up to: 700MHz
- Translates any single-ended input signal to HSTL levels with resistor bias on $\overline{CLK0}$ input
- Output skew: 30ps (maximum)
- Part-to-part skew: 250ps (maximum)
- Propagation delay: 1.8ns (maximum)
- 3.3V core, 1.8V output operating supply
- 0°C to 85°C ambient operating temperature
- Industrial temperature information available upon request
- Available in lead-free (RoHS 6) package
- For functional replacement part use 8523

Block Diagram



Pin Assignment



ICS85214
20-Lead TSSOP
6.5mm x 4.4mm x 0.925mm
package body
G Package
Top View

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Table 1. Pin Descriptions

Number	Name	Type		Description
1, 2	Q0, $\overline{Q0}$	Output		Differential output pair. HSTL interface levels.
3, 4	Q1, $\overline{Q1}$	Output		Differential output pair. HSTL interface levels.
5, 6	Q2, $\overline{Q2}$	Output		Differential output pair. HSTL interface levels.
7, 8	Q3, $\overline{Q3}$	Output		Differential output pair. HSTL interface levels.
9, 10	Q4, $\overline{Q4}$	Output		Differential output pair. HSTL interface levels.
11	GND	Power		Power supply ground.
12	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects differential CLK1input. When LOW, selects CLK0, $\overline{CLK0}$ inputs. LVCMOS/LVTTL interface levels.
13, 17	nc	Unused		No connect.
14	$\overline{CLK0}$	Input	Pullup	Inverting differential clock input.
15	CLK0	Input	Pulldown	Non-inverting differential LVPECL clock input.
16	CLK1	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
18	V_{DD}	Power		Positive supply pin.
19	$\overline{CLK_EN}$	Input	Pulldown	Synchronizing clock enable. When LOW, clock outputs follow clock input. When HIGH, Qx outputs are forced low, $\overline{Qx}$ outputs are forced high. LVTTL/LVCMOS interface levels.
20	V_{DDO}	Power		Output supply pin.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics,* for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
R_{PULLUP}	Input Pullup Resistor			51		kΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			51		kΩ

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Function Tables

Table 3A. Control Input Function Table

Inputs	Outputs	
$\overline{\text{CLK_EN}}$	Q0:Q4	$\overline{\text{Q0:Q4}}$
0	Enabled	Enabled
1	Disabled; LOW	Disabled; HIGH

After $\overline{\text{CLK_EN}}$ switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 1. In the active mode, the state of the outputs are a function of the CLK0, $\overline{\text{CLK0}}$ inputs as described in Table 3B.

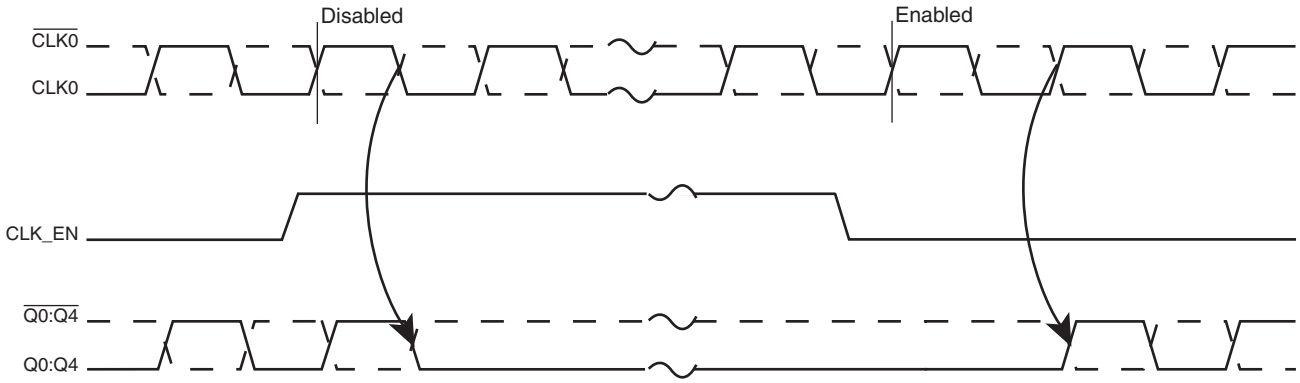


Figure 1. $\overline{\text{CLK_EN}}$ Timing Diagram

Table 3B. Clock Input Function Table

Inputs		Outputs			
CLK0 or CLK1	$\overline{\text{CLK0}}$	Q[0:4]	$\overline{\text{Q[0:4]}}$	Input to Output Mode	Polarity
0	1	LOW	HIGH	Differential to Differential	Non-Inverting
1	0	HIGH	LOW	Differential to Differential	Non-Inverting
0	Biased; NOTE 1	LOW	HIGH	Single-Ended to Differential	Non-Inverting
1	Biased; NOTE 1	HIGH	LOW	Single-Ended to Differential	Non-Inverting
Biased; NOTE 1	0	HIGH	LOW	Single-Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single-Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information section, *Wiring the Differential Input to Accept Single-Ended Levels.*

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Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to V_{DD} + 0.5V
Outputs, V_{DDO}	-0.5V to V_{DD} + 0.5V
Package Thermal Impedance, θ_{JA}	73.2°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDO} = 1.8V ±0.2V, T_A = 0°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Supply Voltage		1.6	1.8	2.0	V
I_{DD}	Power Supply Current				80	mA

Table 4B. LVCMOS/LVTTL DC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDO} = 1.8V ±0.2V, T_A = 0°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage			2		V_{DD} + 0.3	V
V_{IL}	Input Low Voltage			-0.3		0.8	V
I_{IH}	Input High Current	CLK1, $\overline{CLK_EN}$, CLK_SEL	V_{DD} = V_{IN} = 3.465V			150	µA
I_{IL}	Input Low Current	CLK1, $\overline{CLK_EN}$, CLK_SEL	V_{DD} = 3.465V, V_{IN} = 0V	-5			µA

Table 4C. Differential DC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDO} = 1.8V ±0.2V, T_A = 0°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	$\overline{CLK}$	V_{DD} = V_{IN} = 3.465V			5	µA
		CLK	V_{DD} = V_{IN} = 3.465V			150	µA
I_{IL}	Input Low Current	$\overline{CLK}$	V_{DD} = 3.465V, V_{IN} = 0V	-150			µA
		CLK	V_{DD} = 3.465V, V_{IN} = 0V	-5			µA
V_{PP}	Peak-to-Peak Voltage; NOTE 1			0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2			0.5		V_{DD} – 0.85	V

NOTE 1: V_{IL} should not be less than -0.3V.
NOTE 2: Common mode input voltage is defined as V_{IH}.

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Table 4D. HSTL DC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDO} = 1.8V ±0.2V, T_A = 0°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Current; NOTE 1		1.0		1.4	V
V_{OL}	Output Low Current; NOTE 1		0		0.4	V
V_{OX}	Output Crossover Voltage		38% x (V_{OH} – V_{OL}) + V_{OL}		60% x (V_{OH} – V_{OL}) + V_{OL}	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.1	V

NOTE 1: Outputs termination with 50Ω to ground.

AC Electrical Characteristics

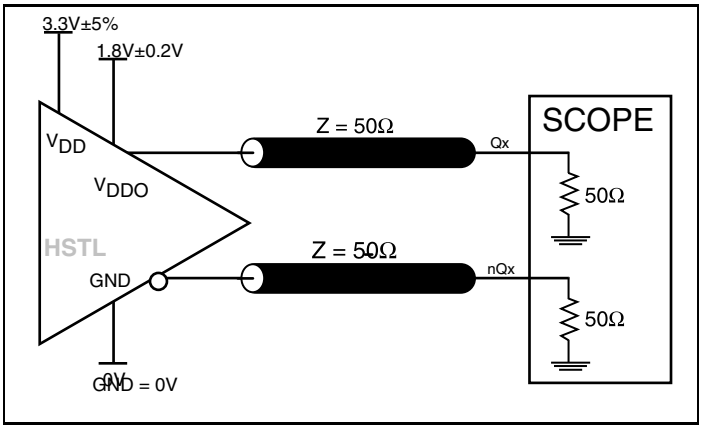
Table 5. AC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDO} = 1.8V ±0.2V, T_A = 0°C to 85°C

Parameter	Symbol		Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency	CLK0, $\overline{CLK0}$				700	MHz
		CLK1				300	MHz
t_{PD}	Propagation Delay; NOTE 1		$f \leq$ 700MHz	1.0		1.8	ns
*t*sk(o)	Output Skew; NOTE 2, 4					30	ps
*t*sk(pp)	Part-to-Part Skew; NOTE 3, 4					250	ps
t_R / t_F	Output Rise/Fall Time		20% to 80%	200		700	ps
odc	Output Duty Cycle	CLK0, $\overline{CLK0}$		46		54	%
		CLK1		45		55	%

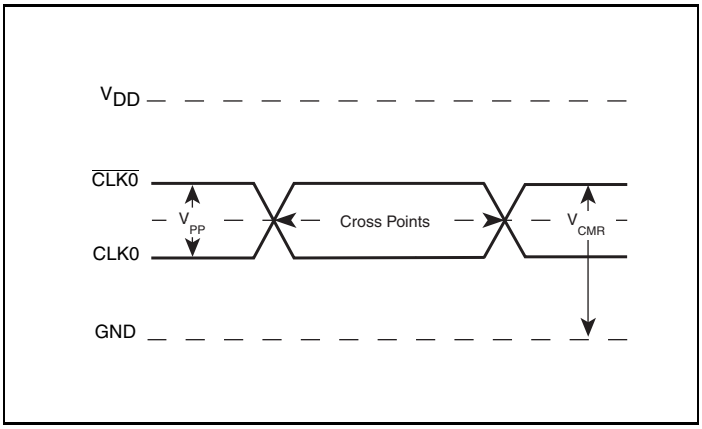
All parameters measured at $_{fMAX}$ unless noted otherwise.
The cycle to cycle jitter on the input will equal the jitter on the output. The part does not add jitter.
NOTE 1: Measured from either the differential input crossing point or VDD/2 to the differential output crossing point.
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.
Measured at output differential cross points.
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions.
Using the same type of inputs on each device, the outputs are measured at the differential cross points.
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.Parameter Measurement Information

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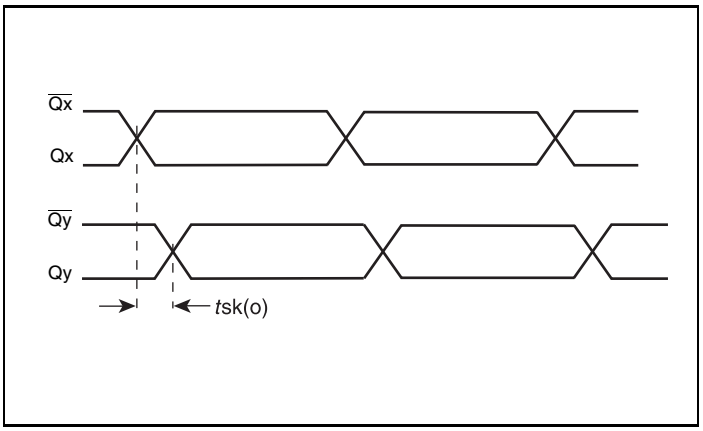
Parameter Measurement Information



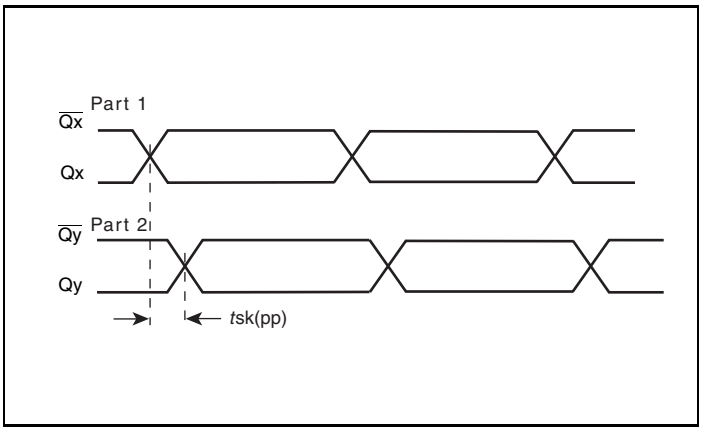
3.3V/1.8V Output Load AC Test Circuit



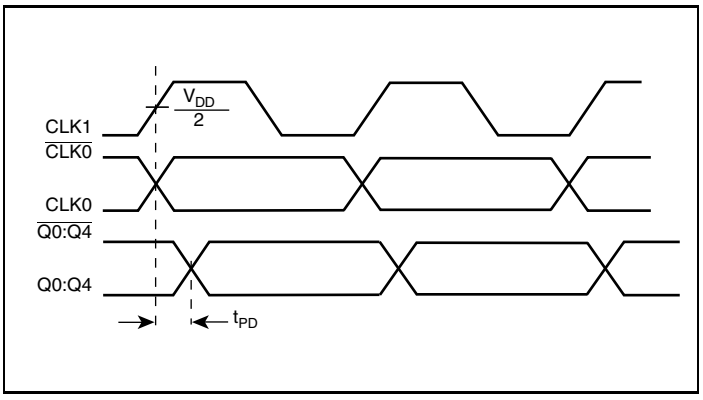
Differential Input Level



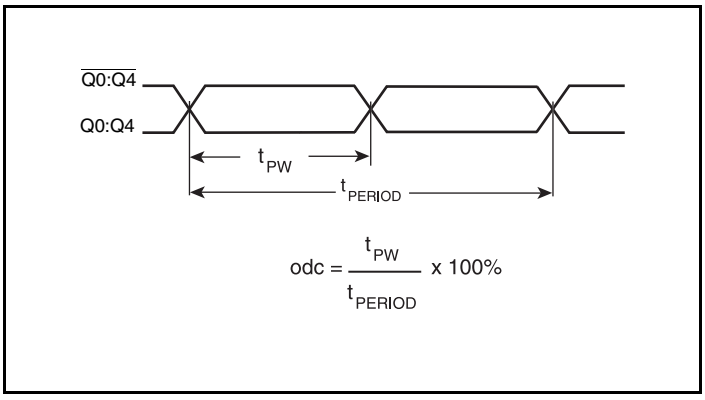
Output Skew



Part-to-Part Skew



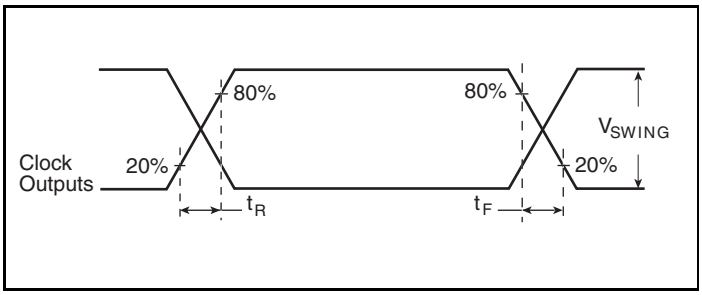
Propagation Delay



Output Duty Cycle/Pulse Width/Period

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Parameter Measurement Information, continued



Output Rise/Fall Time

Application Information

Wiring the Differential Input to Accept Single Ended Levels

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage V_REF = V_{DD}/2 is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and V_{DD} = 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.

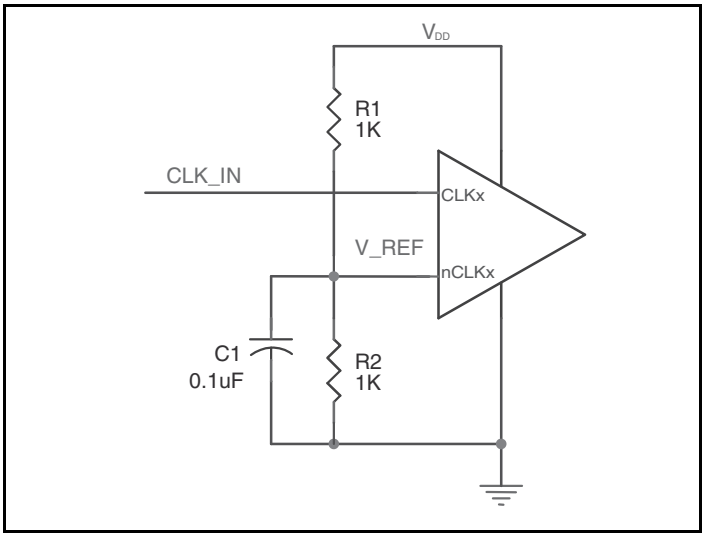


Figure 2. Single-Ended Signal Driving Differential Input

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Differential Clock Input Interface

The CLK /$\overline{CLK}$ accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. *Figures 3A to 3F* show interface examples for the HiPerClockS CLK/$\overline{CLK}$ input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example, in Figure 3A, the input termination applies for IDT HiPerClockS open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

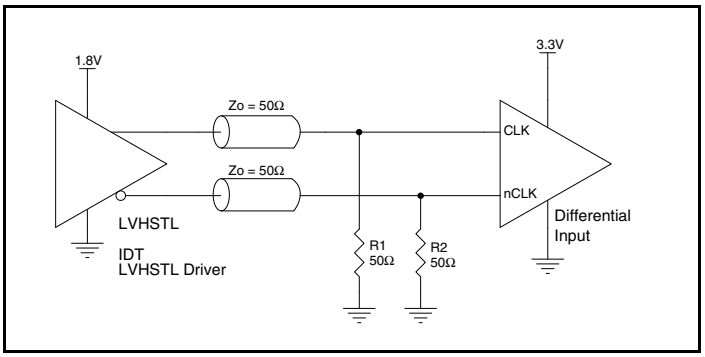


Figure 3A. HiPerClockS CLK/$\overline{CLK}$ Input Driven by an IDT Open Emitter HiPerClockS LVHSTL Driver

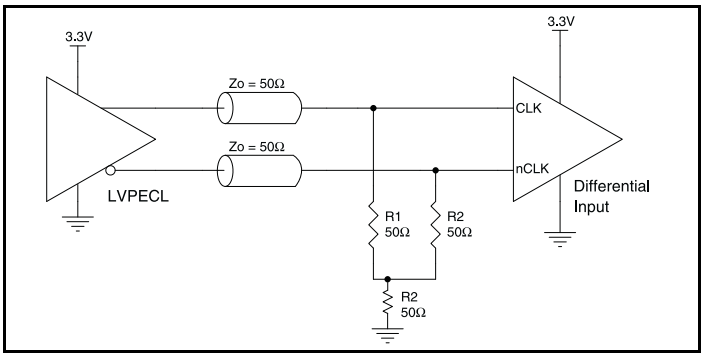


Figure 3B. HiPerClockS CLK/$\overline{CLK}$ Input Driven by a 3.3V LVPECL Driver

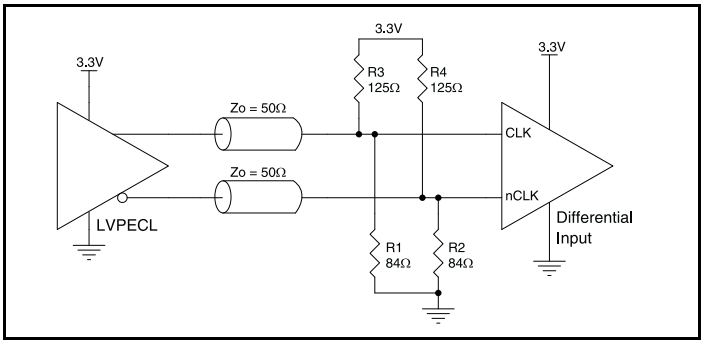


Figure 3C. HiPerClockS CLK/$\overline{CLK}$ Input Driven by a 3.3V LVPECL Driver

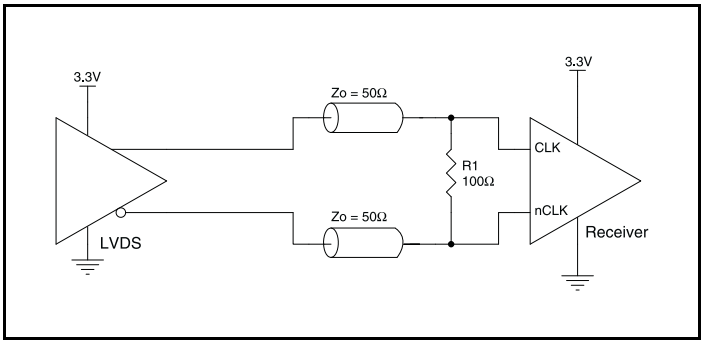


Figure 3D. HiPerClockS CLK/$\overline{CLK}$ Input Driven by a 3.3V LVDS Driver

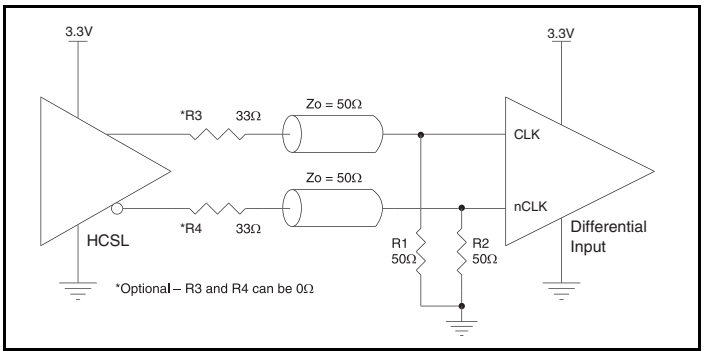


Figure 3E. HiPerClockS CLK/$\overline{CLK}$ Input Driven by a 3.3V HCSL Driver

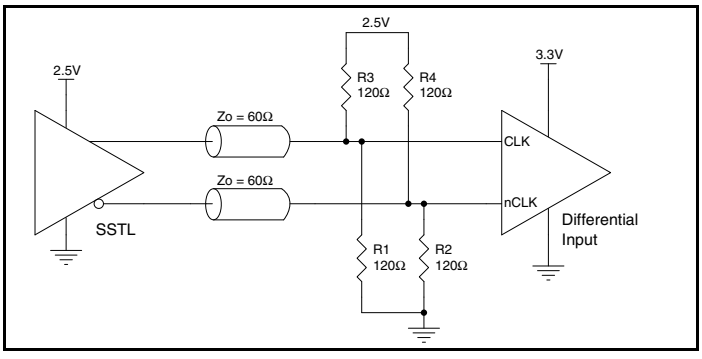


Figure 3F. HiPerClockS CLK/$\overline{CLK}$ Input Driven by a 2.5V SSTL Driver

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Recommendations for Unused Input and Output Pins

Inputs:

LVCMOS Control Pins

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

CLK/$\overline{CLK}$ Inputs

For applications not requiring the use of the differential input, both CLK and $\overline{CLK}$ can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from CLK0 to ground.

CLK Input

For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from the CLK input to ground.

Outputs:

HSTL Outputs

All unused HSTL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

Schematic Example

Figure 4 shows a schematic example of the ICS85214. In this example, the input is driven by an IDT HiPerClockS HSTL driver. The decoupling capacitors should be physically located near the power pin. For ICS85214, the unused clock outputs can be left floating.

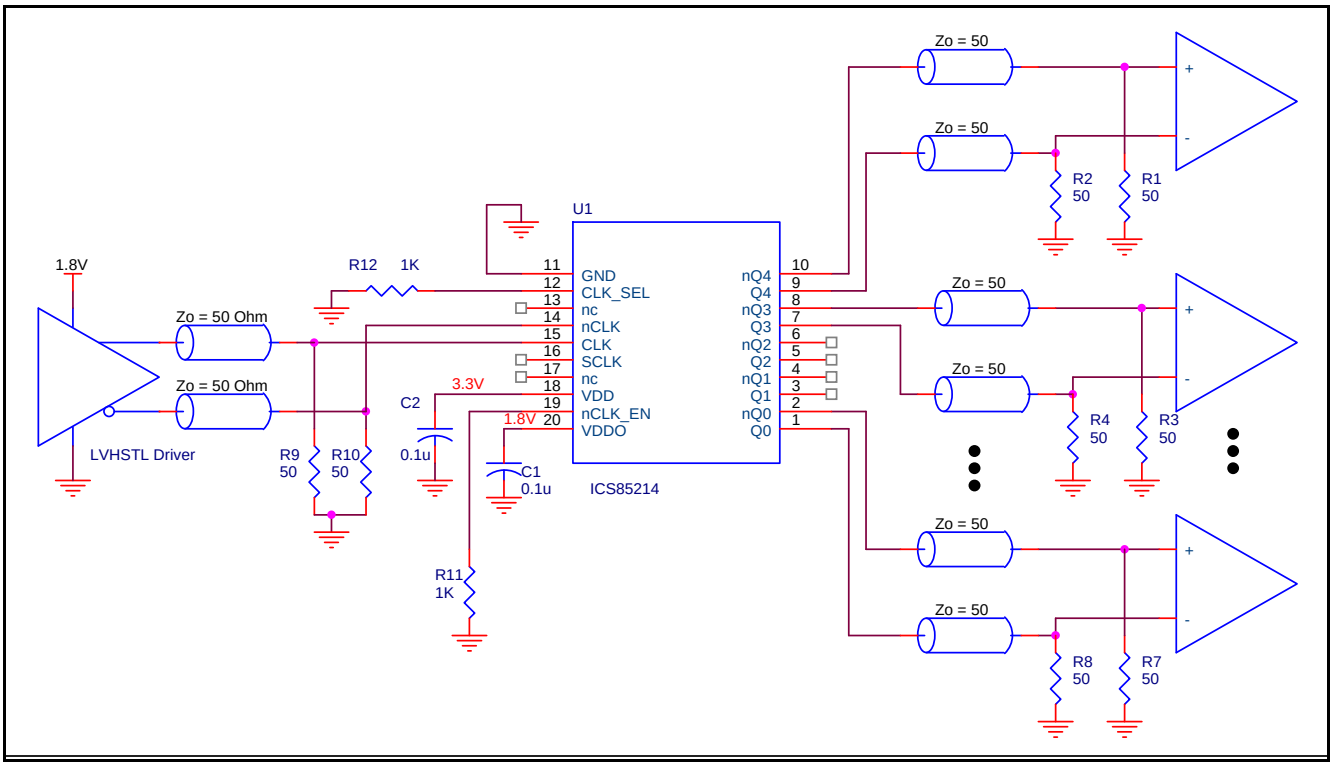


Figure 4. ICS85214 HSTL Buffer Schematic Example

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Power Considerations

This section provides information on power dissipation and junction temperature for the ICS85214.
Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS85214 is the sum of the core power plus the power dissipated in the load(s).
The following is the power dissipation for V_{DD} = 3.3V + 5% = 3.465V, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power $(core)_{MAX} = V_{DD_MAX} * I_{DD_MAX}$ = 3.465V * 850mA = **227.2mW**
- Power $(outputs)_{MAX}$ = **32.8mW/Loaded Output pair**
  If all outputs are loaded, the total power is 5 x 32.8mW = **164mW**

Total Power$_{MAX}$ (3.465V, with all outputs switching) = 227.2mW + 144mW = **391.2mW**

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C.

The equation for Tj is as follows: $Tj = \theta_{JA} * Pd_total + T_A$

Tj = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 66.6°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

85°C + 0.391W * 66.6°C/W = 111°C. This is well below the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (single layer or multi-layer).

Table 6. Thermal Resitance θ_{JA} for 20 Lead TSSOP, Forced Convection

θ_{JA} by Velocity			
Linear Feet per Minute	**0**	**200**	**500**
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

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3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

HSTL output driver circuit and termination are shown in *Figure 6.*

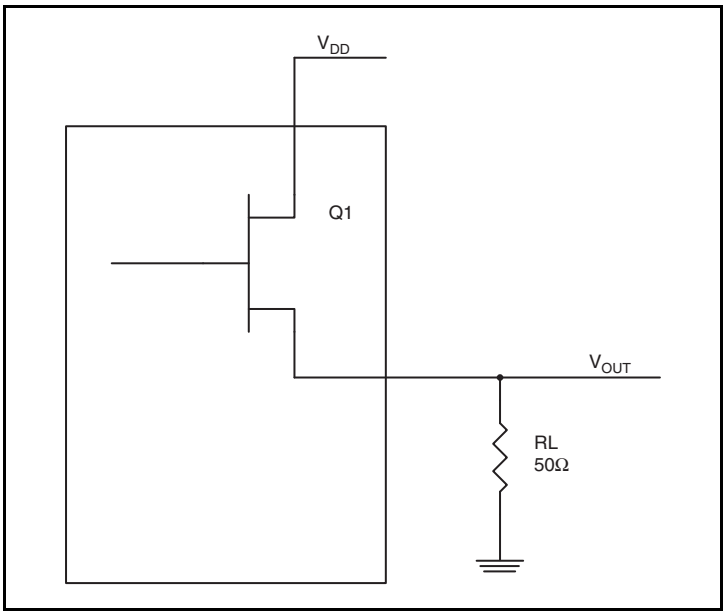


Figure 6. HSTL Driver Circuit and Termination

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load.

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$Pd_H = (V_{OH_MAX}/R_L) * (V_{DDO_MAX} - V_{OH_MAX})$

$Pd_L = (V_{OL_MAX}/R_L) * (V_{DDO_MAX} - V_{OL_MAX})$

Pd_H = (1.0V/50Ω) * (2V - 1.0V) = **20mW**

Pd_L = (0.4V/50Ω) * (2V - 0.4V) = **12.8mW**

Total Power Dissipation per output pair = Pd_H + Pd_L = **32.8mW**

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Reliability Information

Table 7. θ_{JA} vs. Air Flow Table for a 20 Lead TSSOP

θ_{JA} by Velocity			
Linear Feet per Minute	**0**	**200**	**500**
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

Transistor Count

The transistor count for ICS85214 is: 674

Package Outline and Package Dimension

Package Outline - G Suffix for 20 Lead TSSOP

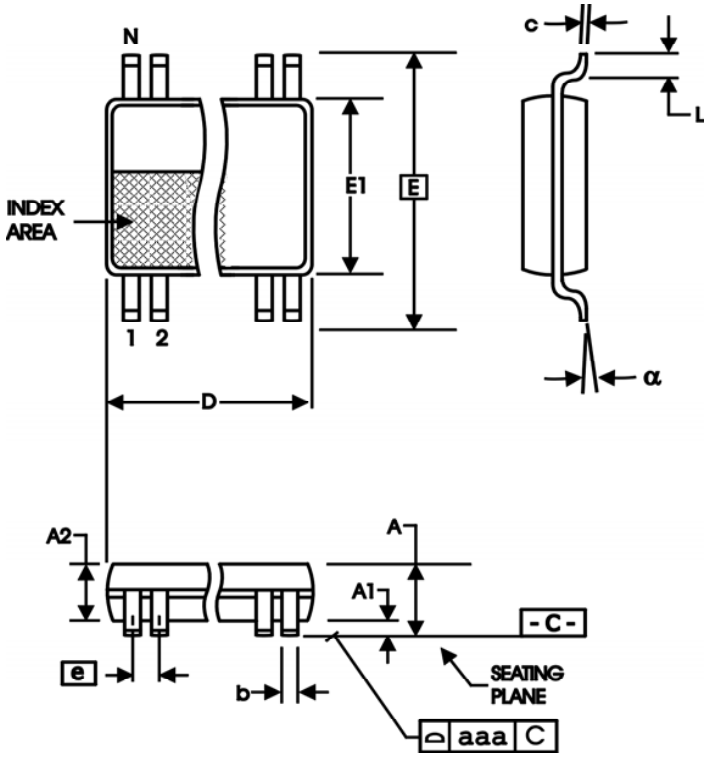


Table 8. Package Dimensions

All Dimensions in Millimeters		
Symbol	**Minimum**	**Maximum**
N	20	
A		1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 Basic	
E1	4.30	4.50
e	0.65 Basic	
L	0.45	0.75
α	0°	8°
aaa		0.10

Reference Document: JEDEC Publication 95, MO-153

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Ordering Information

Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
85214AGLF	ICS85214AGLF	“Lead-Free” 20 Lead TSSOP	Tube	0°C to 85°C
85214AGLFT	ICS85214AGLF	“Lead-Free” 20 Lead TSSOP	2500 Tape & Reel	0°C to 85°C

NOTE: "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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Revision History Sheet

Rev	Table	Page	Description of Change	Date
A	T2	2	Changed LVHSTL to HSTL throughout the datasheet. Pin Characteristics Table - changed C_{IN} 4pF max. to 4pF typical	7/17/03
A	T9	1 9 13	Features Section - added Lead-Free Bullet. Added *Recommendation of Unused Input and Output Pins.* Ordering Information Table - added Lead-Free part number, marking, and note. Changed format throughout the datasheet.	3/13/07
B	T3B	3 8	Clock Input Function Table - corrected $\overline{CLK0}$ column from 0 (1st row) to 1 and 1 (2nd row) to 0. Updated *Differential Clock Input Interface section*.	2/25/08
B	T9	13	Removed leaded orderable parts from Ordering Information table	11/15/12
B			Product Discontinuation Notice - Last time buy expires May 6, 2017. PDN CQ-16-01	6/3/16

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